

## Surface-Mount Glass Passivated Rectifier



**SMC (DO-214AB)**

Cathode  Anode



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### FEATURES

- Low profile package
- Ideal for automated placement
- Glass passivated pellet chip junction
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

### LINKS TO ADDITIONAL RESOURCES



### TYPICAL APPLICATIONS

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.

### MECHANICAL DATA

**Case:** SMC (DO-214AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-E3 - RoHS-compliant, commercial grade

Base P/N-M3 - halogen-free, RoHS-compliant, commercial grade

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

E3 and M3 suffix meets JESD 201 class 2 whisker test

**Polarity:** color band denotes cathode end

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	8.0 A
$V_{RRM}$	400 V, 600 V, 800 V, 1000 V
$I_{FSM}$	200 A
$I_R$	10 $\mu$ A
$V_F$ at $I_F = 8$ A ( $T_J = 125$ °C)	0.87 V
$T_J$ max.	150 °C
Package	SMC (DO-214AB)
Circuit configuration	Single

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)						
PARAMETER	SYMBOL	S8GS	S8JS	S8KS	S8MS	UNIT
Device marking code		S8GS	S8JS	S8KS	S8MS	
Maximum repetitive peak reverse voltage	$V_{RRM}$	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}^{(1)}$	8.0				A
	$I_{F(AV)}^{(2)}$	1.6				A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	200				A
Peak forward surge current single half sine-wave at 1.0 ms	$I_{FSM}$	450				A
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150				°C

#### Notes

(1) Mounted on aluminum PCB 30 mm x 30 mm with aluminum heatsink

(2) Free air, mounted on recommended copper pad area

ELECTRICAL CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 4.0 A	T <sub>J</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.90	-	V
	I <sub>F</sub> = 8.0 A			0.97	0.985	
	I <sub>F</sub> = 4.0 A	T <sub>J</sub> = 125 °C		0.80	-	
	I <sub>F</sub> = 8.0 A			0.87	0.971	
Reverse current	Rated V <sub>R</sub>	T <sub>J</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	10	μA
		T <sub>J</sub> = 125 °C		-	180	
Typical reverse recovery time	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 0.25 A		t <sub>rr</sub>	3.4	-	μs
Typical junction capacitance	4.0 V, 1 MHz		C <sub>J</sub>	63	-	pF

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width; 1 % duty cycle  
(2) Pulse test: pulse width  $\leq 40\text{ ms}$

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	S8GS	S8JS	S8KS	S8MS	UNIT
Typical thermal resistance	R <sub>θJA</sub> <sup>(1)(2)</sup>	88				°C/W
	R <sub>θJM</sub> <sup>(3)</sup>	4.5				

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/R_{\theta JA}$   
(2) Thermal resistance junction-to-ambient to follow JEDEC<sup>®</sup> 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint  
(3) Thermal resistance junction-to-mount to follow JEDEC<sup>®</sup> 51-14 transient dual interface test method (TDIM)

<b>ORDERING INFORMATION</b> (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
S8JS-E3/I	0.243	I	3500	13" diameter plastic tape and reel
S8JS-M3/I	0.243	I	3500	13" diameter plastic tape and reel

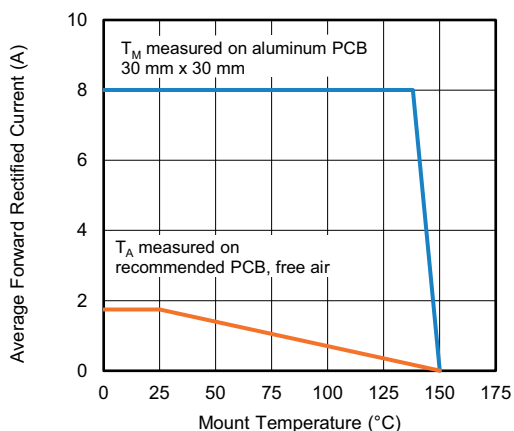
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Forward Current Derating Curve

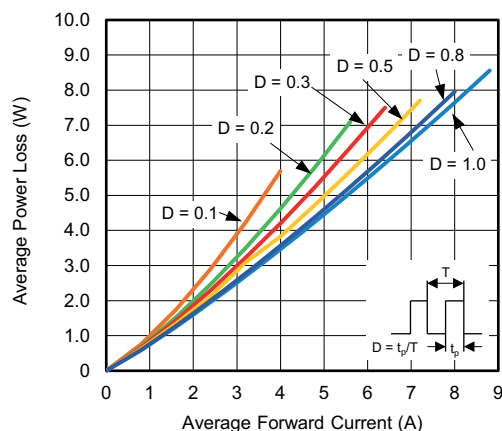


Fig. 2 - Average Power Loss Characteristics

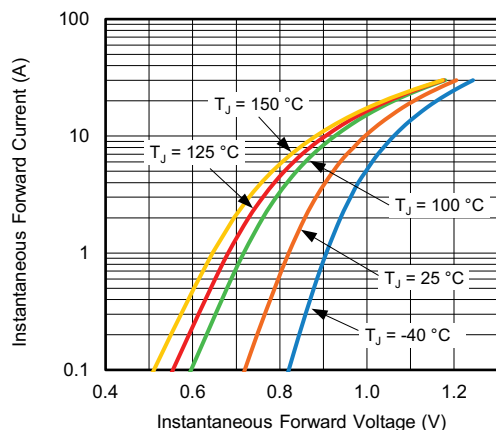


Fig. 3 - Typical Instantaneous Forward Characteristics

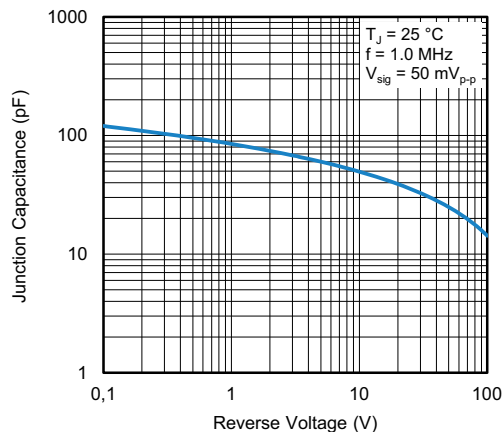


Fig. 5 - Typical Junction Capacitance

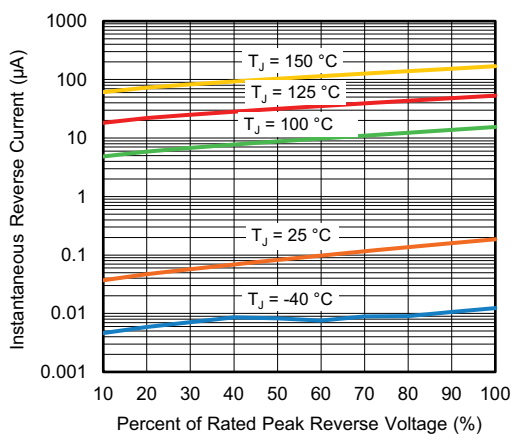


Fig. 4 - Typical Reverse Characteristics

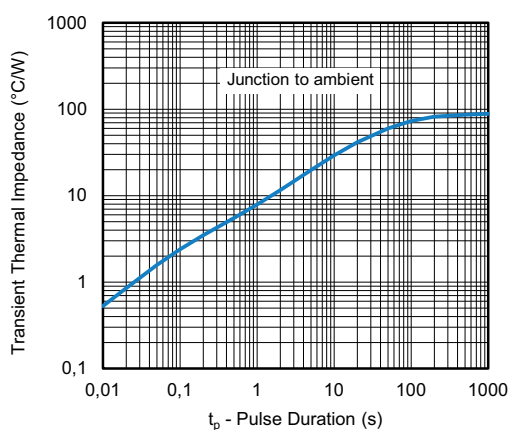
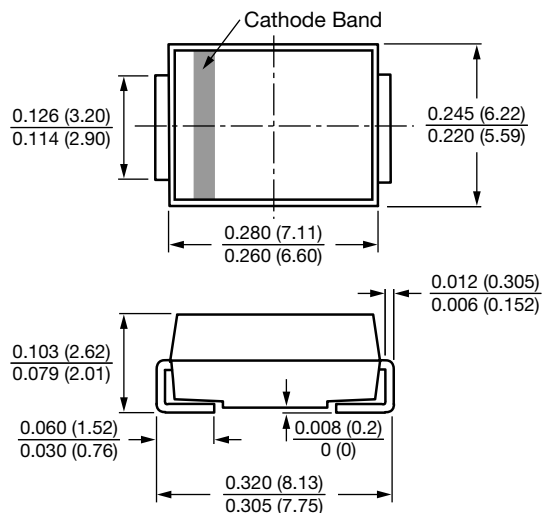
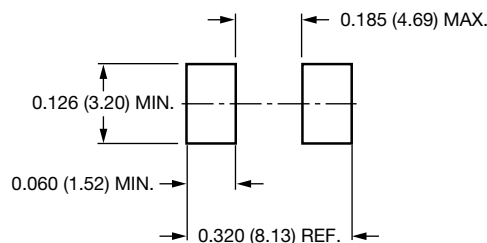


Fig. 6 - Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

**SMC (DO-214AB)**

**Mounting Pad Layout**




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